

## TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

<b>Title of Invention</b>	[STACK-TYPE MULTI-CHIP PACKAGE AND METHOD OF FABRICATING BUMPS ON THE BACKSIDE OF A CHIP]							
Application Number :								
Date :								
First Named Applicant:	Mr. Chih-Huang Chang							
Confirmation Number:								
Attorney Docket Number:	10544-US-PA							
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<table border="1"><tr><td>Submitted By:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>Dr. Belinda Lee Registered Number: 46,863</td><td>/Belinda Lee/</td><td>Agent</td></tr></table>			Submitted By:	Elec. Sign.	Sign. Capacity	Dr. Belinda Lee Registered Number: 46,863	/Belinda Lee/	Agent
Submitted By:	Elec. Sign.	Sign. Capacity						
Dr. Belinda Lee Registered Number: 46,863	/Belinda Lee/	Agent						

Documents being submitted:	Files
us-assignment	10544-usassn.xml us-assignment.xsl us-assignment.dtd 10544assignment01.tif 10544assignment02.tif
us-request	10544-usrequ.xml us-request.dtd us-request.xsl
us-fee-sheet	10544-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
application-body	10544-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd 10544us0001.tif 10544us0002.tif 10544us0003.tif 10544us0004.tif 10544us0005.tif 10544us0006.tif 10544us0007.tif 10544us0008.tif
us-declaration	10544declaration01.tif
us-declaration	10544declaration02.tif

**Comments**

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